ABSTRACT

It is an object of the present invention to provide a windowed polishing pad or a platen hole cover which is used to form planar surfaces in glass, semiconductors, dielectric/metal composites, integrated circuits, etc.; a polishing apparatus including the windowed polishing pad or the platen hole cover; a method for fabricating a semiconductor device using the polishing apparatus; and a polishing method, in which the number of scratches occurring on the surface of the substrate is small, and the polished state can be optically measured satisfactorily during polishing.

In order to achieve the above object, a polishing pad is constructed in such a manner that the polishing pad includes a polishing layer and a light-transmissive window member disposed in an opening formed in a part of the polishing layer, wherein the amount of indentation strain measured when a constant load is applied to substantially the entire upper surface of the light-transmissive window member is larger than the amount of indentation strain measured when the same constant load is applied to a region having the same area on the upper surface of the polishing layer.